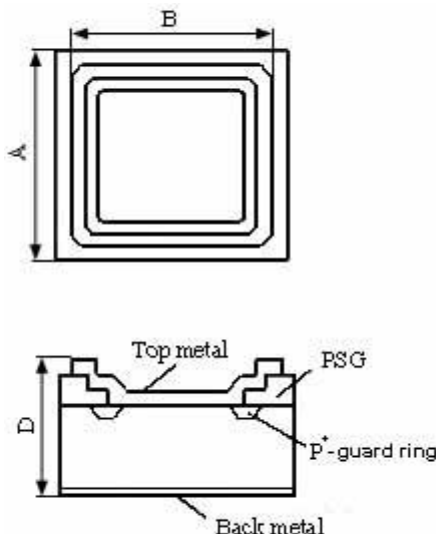
mikron VSP-MIKRON

	10A/60V. Die Size-106mil.			
Electrical Characteristics	**Symbol**	**Unit**	**Spec. limit**	**Die Sort**
Breakdown Voltage @ I_R=10mA	V_{BR}	V	60	65
Average Rectified Forward Current	$I_{F(AV)}$	A	10,0	-
DC Forward Voltage @ 25˚C, I_F=10,0A; @ 25˚C, I_F=20,0A;	V_F	V	0,59 0,71	0,57 0,70
Maximum Reverse Current @ 25˚C, V_R=65V @ 25˚C, V_R=60V @ 125˚C, V_R=60V	I_R	mA	- 0,120 65,0	0,12 0,08 60,0
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	I_{FSM}	A	180	-
Peak Repetitive Reverse Surge Current @ 2,0µs, f=1kHz., T_J<150˚C.	I_{RRM}	A	4,0	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	ESD	kV	±8 (contact)	
Voltage Rate of Change	dV/dt	V/µS	10.000	
Operating Junction Temperature	T_J	˚C	150	



DIM	ITEM	µm
A_X A_Y	Wafer Form Die Size	2700 2700
B_X B_Y	Top Metal Size	2560 2560
D	Thickness	350max.
Scribe line Width		80

Top metal:
a) **Al** – for Wire Bonding;
b) **Al-Ni-Ag** – for Soldering.
Backside metal: **Ti-Ni-Ag**.